New Product Introduction

January 2026

CoolGaN™ Drive HB 600 V G5

XHP™ 2 2300 V IGBT7

Easy module CoolSiC 1200 V and Si IGBT (and CoolMOS™) OBC and EV AUX

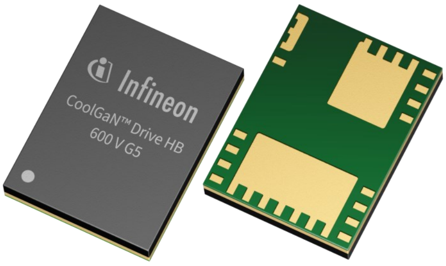
XENSIV™ MEMS microphone IM67D128B

Door control module reference design featuring MOTIX™ SBC TLE9562, MOTIX™ Bridge TLE9166EQ, BTM90x1 and TRAVEO™ II microcontroller

AURIX™ Drive Core AUTOSAR [Infineon, iSoft, Tasking] V1.0

CoolGaN™ Drive HB 600 V G5

The CoolGaN™ Drive HB 600 V G5 family combines a half-bridge power stage consisting of two CoolGaN™ Transistors 600 V G5 with an integrated level-shift gate driver and a bootstrap diode in a small 6x8 TFLGA-27 package.



Features

- Integrated level shift gate driver
- Integrated bootstrap diode
- PWM input compatible
- Wide VDD range (10 to 24 V)
- Turn-on and off dv/dt slew rate control
- Zero Q_{RR}

Benefits

- 4x reduction in component count
- 2x reduction of footprint on a PCB
- Reduced cost
- Reduced weight
- Reduced complexity

Competitive advantage

- Fast switching: 98 ns propagation delay with minimal mismatch
- Thermal management: 6 x 8 mm TFLGA-27 package. 27 pins with exposed pads for thermal management
- Single supply voltage: 12 V gate driver supply with fast UVLO recovery
- Robust design: JEDEC-qualified for industrial applications

Target applications

- USB-C adapters and chargers
- Mixer – variable speed DC and SRM motors
- Low-power motor drives
- Switched-mode power supplies for low-power applications

Product collaterals / Online support

Product page IGI60L1414B1MXUMA1

Product page IGI60L2727B1MXUMA1

Product page IGI60L5050B1MXUMA1

Product overview incl. datasheet link

OPN	SP Number	Package
IGI60L1414B1MXUMA1	SP005987622	PG-TFLGA-27
IGI60L2727B1MXUMA1	SP005865980	PG-TFLGA-27
IGI60L5050B1MXUMA1	SP005906824	PG-TFLGA-27

XHP™ 2 2300 V IGBT7

Extending XHP^{TM} 2 portfolio addressing raising trend of higher DC-link applications as renewables and more with new 2300 V, 1400 A dual IGBT module with TRENCHSTOP™ IGBT7 offering outstanding higher power density and efficiency for high-power applications with 6 kV isolation voltages.

Available with pre-applied Thermal Interface Material (TIM) for simplified assembly and optimal thermal performance.

Features

- Low-inductive housing XHP™ 2
- Symmetrical module design
- T_{vj} = 175°C continuous
- Package with CTI > 600
- 6 kV isolation voltage
- AlSiC baseplate

Benefits

- Energy efficiency
- High power density
- Consistent performance in harsh environments
- Easier paralleling of modules

Competitive advantage

- Blocking voltage of 2300 V with 6 kV isolation voltage enables addressing 3-level topologies with DC-link voltage up to 3000 V
- Material composition allowing T_{vjop} = 175°C ensures better performance under challenging environmental conditions
- High cycling endurance

Target applications

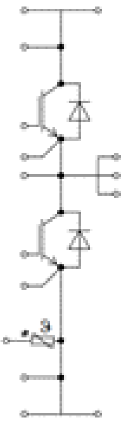
- Wind
- ESS
- PV
- Traction

Product collaterals / Online support

[Product page FF1400R23T2E7B5BPSA1]

[Product page FF1400R23T2E7PB5BPSA1]

Block diagram



Product overview incl. datasheet link

OPN	SP Number	Package
FF1400R23T2E7B5BPSA1	SP006136008	AG-XHP2K23-731
FF1400R23T2E7PB5BPSA1	SP006140104	AG-XHP2K23-731

Easy module CoolSiC 1200 V and Si IGBT (and CoolMOS™) OBC and EV AUX

AQG324-qualified EasyPACK™ integrates the advanced capabilities of the CoolMOS™ CFD7A 650 V, offering an ideal balance of cost and performance for on-board charger and EV auxiliary applications.

Features

- Highly reliable press-fit pins
- Pre-applied thermal interface material
- Enables compact design
- Integration of SMD possible

Benefits

- Very good pin-PCB connection
- Better thermal performance
- Reduced assembly efforts
- Higher degree of freedom in terms of design

Competitive advantage

- Reduced system costs and high system reliability

Target applications

- DC charger for EV
- On Board Charger
- High frequency switching application

Product collaterals / Online support

Product page

Product overview incl. datasheet link

OPN	SP Number	Package
F899MR07W1D7B11ABPSA1	SP005742275	AG-EASY1B-9021

XENSIV™ MEMS microphone IM67D128B

IM67D128B is an ultra-low power digital XENSIV™ MEMS microphone, designed for applications which require long battery life and environmental robustness in an exceptionally small package. With a Signal-to-Noise Ratio (SNR) of 67 dB(A) and low corner frequency of 10 Hz the microphone enables a clear audio experience without compromising on battery life. Enabled by a revolutionary digital microphone ASIC, the IM67D128B balances performance in a very small package with low current consumption of 540 µA.

Features

- Low current consumption in high performance mode (540 µA)
- Ultra-low current consumption in low power mode (170 µA)
- Signal-to-Noise Ratio (SNR) of 67 dB(A)
- Acoustic overload point at 128 dBSPL
- Flat frequency response with low frequency roll-off at 10 Hz
- Component level IP57 dust and water resistant
- Package dimensions: 3mm x 2mm x 0.98mm
- Enhanced RF shielding
- Digital PDM output
- Bottom port

Benefits

- Strong acoustic performance with small footprint and low current consumption
- Clear audio signals even for high sound pressure levels
- Highest precision of audio beams and algorithms

Competitive advantage

- New Single Backplate (SBP) technology
- Ultra-low current consumption in low power mode (170 µA)
- Component level IP57 water and dust resistant

Target applications

- Active Noise Cancellation (ANC): headphones and earphones
- Smartphones and mobile devices
- Hearing enhancement devices
- Voice User Interface (VUI): e.g., smart speaker, home automation and IOT devices
- Power constrained applications

Product collaterals / Online support

[Product page]

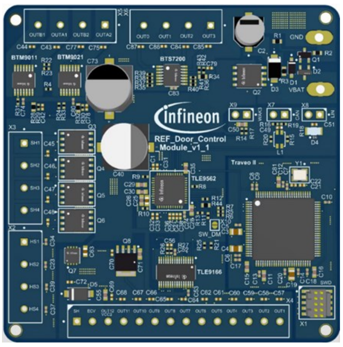
Product overview incl. datasheet link

OPN	SP Number	Package
IM67D128BV01XTMA1	SP006037658	PG-TLGA-5

Door control module reference design featuring MOTIX™ SBC TLE9562, MOTIX™ Bridge TLE9166EQ, BTM90x1 and TRAVEO™ II microcontroller

Infineon’s comprehensive door control module system solution offers robust, size-optimized hardware. The system features several MOTIX™ motor control ICs, including the TLE9166EQ multi-half bridge IC, the BTM90x1 full-bridge IC, and the TLE9562 motor system IC (SCB), as well as the PROFET™ BTS7200 high-side switch, the OptiMOS™ 7 MOSFET, and the TRAVEO™ II microcontroller, which allows for efficient integration.

Furthermore, there is an application-embedded software project with multiple MOTIX™ device drivers and a TRAVEO™ II sample driver library (SDL) available for seamless implementation and evaluation.



Features

- MOTIX™ SBC TLE9562 (motor system IC)
- MOTIX™ Bridge TLE9166EQ (door control IC)
- MOTIX™ Bridge BTM9011 and BTM9021 (full-bridge ICs)
- PROFET™ BTS7200 high-side switch
- TRAVEO™ II microcontroller
- OptiMOS™ 7 MOSFET
- CAN/LIN interface
- Supply voltage min. 5.5 V and max. 20 V

Benefits

- System level door control module reference design
- Compact PCB board with optimal thermal and EMC performance
- Comprehensive software solutions with various device drivers and application code

Competitive advantage

- Hardware and software system offering
- Compact and robust design with optimal thermal and EMC performance
- Optimized BOM for door module or door zone control with multiple functions
- Extensive user guide with complete test report

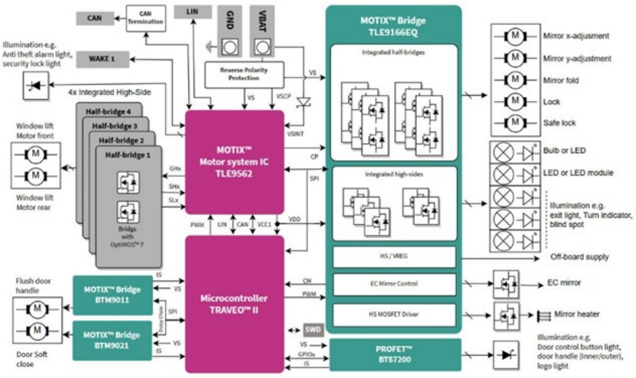
Target applications

- Automotive door control module
- Window lift
- Mirror adjustment
- Flush door handle
- Door soft close
- Illumination, e.g., door control button light, car logo light

Product collaterals / Online support

[Board page]

Block diagram

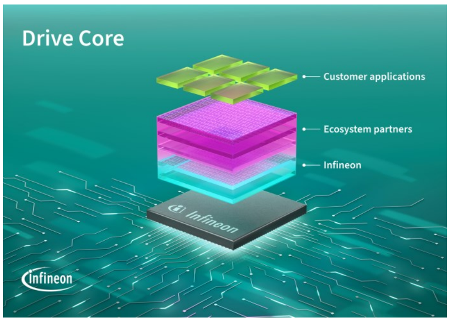


Product overview incl. user guide link

OPN	SP Number	Package
REFDOORCONTROLTOBO1	SP006168504	L-MADK-1

AURIX™ Drive Core AUTOSAR [Infineon, iSoft, TASKING] V1.0

Infineon's new software bundle for the AURIX™ TC4D, developed with iSOFT and TASKING, is your all-in-one solution for efficient AUTOSAR development. It features Infineon's MC-ISAR AURIX™ TC4x drivers for reliable hardware abstraction, iSOFT's ORIENTAIS SWC Builder for streamlined ASW design, ORIENTAIS BSW Configurator for efficient customization, and TASKING's SmartCode C/C++ Compiler Tool Chain for TriCore and PPU. Supporting both ORIENTAIS (commercial) and EasyXMen (open source), the bundle simplifies integration, enhances workflows, and delivers a ready-to-use real-time operating system. By streamlining development processes and reducing complexity, it empowers developers to bring innovative solutions to market faster and more efficiently.



Features

- Infineon's MCAL drivers for reliable hardware abstraction for AURIX™ TC4D
- ORIENTAIS Classic Platform/EasyXMen: Classic Platform AUTOSAR solution for developing and integrating automotive software
- TASKING's TC4x Compiler Tool Chain SmartCode: provides a comprehensive development environment

Benefits

- Immediate evaluation of productive AUTOSAR stack on AURIX TC4x
- Pre-integration and configuration of MCAL and BSW
- Inclusion of all necessary tooling for SWC building, BSW and MCAL configuration and debugging

Competitive advantage

- 3-Month free evaluation: get started risk-free and explore the full potential of the bundle
- All-inclusive licensing: includes all necessary licenses and tools, eliminating the need for complex supplier management and allowing you to start developing immediately
- Compatibility guaranteed: ready-to-use, certified tooling for configuration, debugging, and compilation, ensuring a seamless development experience

Target applications

- AUTOSAR development on AURIX™ TC4D

Product collaterals / Online support

Product page

Block diagram